SDFS042A - MARCH 1987 - REVISED OCTOBER 1993

 Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

#### description

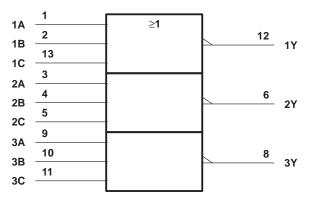
These devices contain three independent 3-input NOR gates. They perform the Boolean functions  $Y = \overline{A} \bullet \overline{B} \bullet \overline{C}$  or  $Y = \overline{A} + \overline{B} + \overline{C}$  in positive logic.

The SN54F27 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125°C. The SN74F27 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE
(each gate)

	INPUTS	OUTPUT	
А	В	С	Y
Н	Х	Х	L
Х	н	Х	L
Х	Х	Н	L
L	L	L	н

#### logic symbol<sup>†</sup>

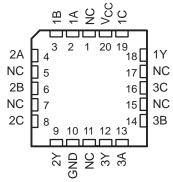


<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

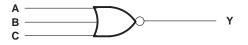
SN54F27 J PACKAGE SN74F27 D OR N PACKAGE (TOP VIEW)										
L		$\nabla$	_							
1A [	1	14	] V <sub>CC</sub> ] 1C							
1B 🛛	2	13	] 1C							
2A [	3	12	] 1Y							
2B 🛛	4	11	] 3C							
2C [	5	10	3B							
2Y [ GND [	6	9	3A							
GND [	7	8	] 3Y							
I I										

SN54F27 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### logic diagram, each gate (positive logic)



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

### SN54F27, SN74F27 TRIPLE 3-INPUT POSITIVE-NOR GATES

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub> Input voltage range, V <sub>I</sub> (see Note 1)	
Input current range	
Voltage range applied to any output in the high state	
Current into any output in the low state	
Operating free-air temperature range: SN54F27	
SN74F27	0°C to 70°C
Storage temperature range	−65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

#### recommended operating conditions

		SN54F27 SN74F27				UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
IIK	Input clamp current			-18			-18	mA
ЮН	High-level output current			- 1			- 1	mA
I <sub>OL</sub>	Low-level output current			20			20	mA
Т <sub>А</sub>	Operating free-air temperature	-55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	те	TEST CONDITIONS				5	SN74F27		UNIT
PARAMETER		STCONDITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V <sub>CC</sub> = 4.5 V,	lj = – 18 mA			-1.2			-1.2	V
Voh	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = – 1 mA	2.5	3.4		2.5	3.4		v
VОН	V <sub>CC</sub> = 4.75 V,	I <sub>OH</sub> = – 1 mA				2.7			
VOL	V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 20 mA		0.3	0.5		0.3	0.5	V
lı	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1			0.1	mA
IIH	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20	μΑ
١ <sub>١L</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.5 V			- 0.6			- 0.6	mA
los§	V <sub>CC</sub> = 5.5 V,	$V_{O} = 0$	-60		-150	-60		-150	mA
Іссн	V <sub>CC</sub> = 5.5 V,	$V_{I} = 0$		3.8	5.5		3.8	5.5	mA
ICCL	V <sub>CC</sub> = 5.5 V,	See Note 2		8.4	12		8.4	12	mA

<sup>‡</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> =  $25^{\circ}$ C.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2:  $\ \mbox{I}_{CCL}$  is measured with one input at 4.5 V and all others grounded.



### SN54F27, SN74F27 TRIPLE 3-INPUT POSITIVE-NOR GATES

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### switching characteristics (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CI RI	V <sub>CC</sub> = 5 V, C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω, T <sub>A</sub> = 25°C			$V_{CC} = 4.5 V \text{ to } 5.5 V,$ $C_L = 50 \text{ pF},$ $R_L = 500 \Omega,$ $T_A = \text{MIN to MAX}^{\dagger}$ SN54F27 SN74F27			
			MIN	′F27 ТҮР	MAX	SN54 MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A, B, or C	V	1.2	3.1	5	1	6	1	5.5	200
<sup>t</sup> PHL	A, B, 01 C	Ť	1	2.1	4.5	1	5.5	1	4.5	ns

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 3: Load circuits and waveforms are shown in Section 1.





#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-89510012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	(6) SNPB	N / A for Pkg Type	-55 to 125	5962- 89510012A SNJ54F27FK	Samples
5962-8951001CA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8951001CA SNJ54F27J	Samples
SN74F27D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F27	Samples
SN74F27DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F27	Samples
SN74F27DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F27	Samples
SN74F27N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74F27N	Samples
SN74F27NE4	ACTIVE	PDIP	N	14	25	TBD	Call TI	Call TI	0 to 70		Samples
SN74F27NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F27	Samples
SNJ54F27FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 89510012A SNJ54F27FK	Samples
SNJ54F27J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8951001CA SNJ54F27J	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.



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### PACKAGE OPTION ADDENDUM

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54F27, SN74F27 :

Catalog : SN74F27

• Military : SN54F27

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

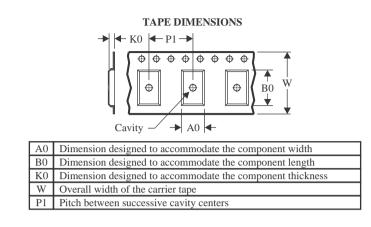


Texas

STRUMENTS

#### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All	dimensions are nominal												
Γ	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74F27DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN74F27NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

#### Pack Materials-Page 1



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## PACKAGE MATERIALS INFORMATION

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F27DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74F27NSR	SO	NS	14	2000	356.0	356.0	35.0

### TEXAS INSTRUMENTS

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### TUBE



### - B - Alignment groove width

#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-89510012A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74F27D	D	SOIC	14	50	506.6	8	3940	4.32
SN74F27N	N	PDIP	14	25	506	13.97	11230	4.32
SN74F27N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54F27FK	FK	LCCC	20	1	506.98	12.06	2030	NA

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N\*\*) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



### MECHANICAL DATA

#### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## **GENERIC PACKAGE VIEW**

## CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



## J0014A



## **PACKAGE OUTLINE**

### CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
  Falls within MIL-STD-1835 and GDIP1-T14.



## J0014A

## **EXAMPLE BOARD LAYOUT**

### CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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